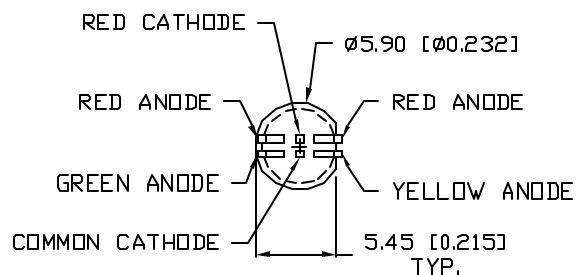
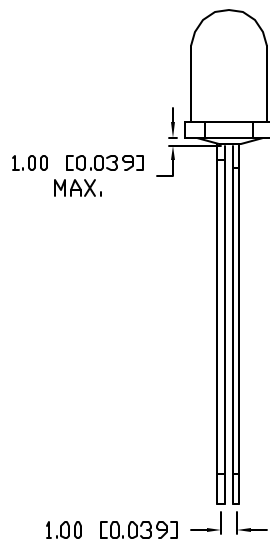
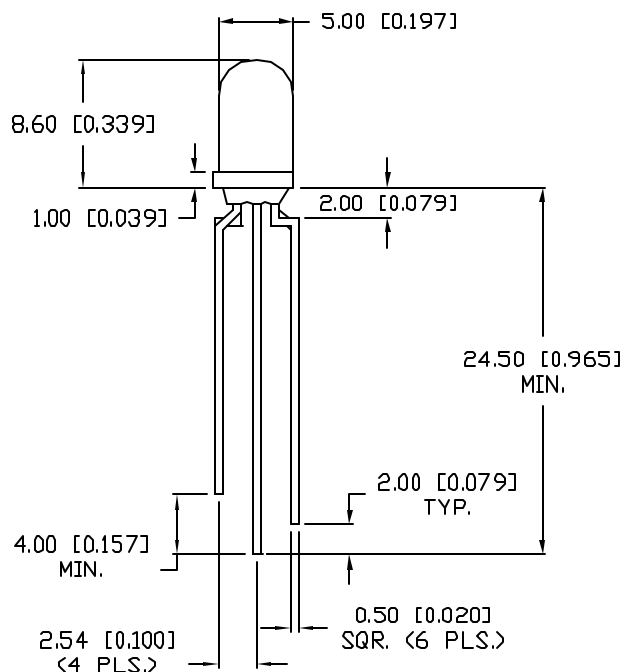
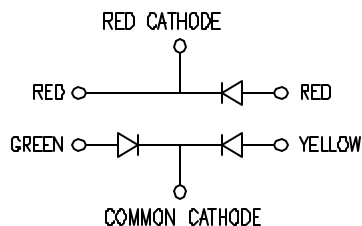


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PART NUMBER		REV.
SSL-LX5099SISYSUGC		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11148	11.08.06



BOTTOM VIEW POLARITY



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636 (RED)		nm	
		574 (GREEN)		nm	
		590 (YELLOW)		nm	
FORWARD VOLTAGE (R)		1.9	2.5	$V_f$	
	(G)		2.1	2.5	$V_f$
	(Y)		2.0	2.5	$V_f$
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY (R/G/Y)		800/450/500		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		30		2x theta	
EMITTED COLOR:	RED/GREEN/YELLOW (MULTI-COLOR)				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*	(R/G/Y)	185/150/150	mA
STEADY CURRENT		30	mA
POWER DISSIPATION	(R/G/Y)	170/105/125	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING, STORAGE TEMP.		-40 TO +85	°C
SOLDERING TEMP.		+260	°C
2.0mm FROM BODY			3 SEC. MAX

\*  $t < 10\mu\text{s}$



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\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN. <sup>+DECIMAL PRECISION</sup> -0.00 <sup>MAX. = +0.00</sup> -DECIMAL PRECISION

REV.	PART NUMBER
A	SSL-LX5099SISYSUGC

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T-5mm (T-1 3/4) LED, 6 LEADED, MULTI-COLORED,  
 636nm AlInGaP RED/574nm AlInGaP GREEN,  
 590nm AlInGaP YELLOW, WATER CLEAR LENS.

RELIABILITY NOTE  
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 11.08.06
JC			PAGE: 1 OF 1
			SCALE: N/A